

Silicon Carbide Power MOSFET Switching Optimized 1200V $65m\Omega$ Automotive N-Channel Enhancement Mode

Features

- Industry compatible drive voltage 15V...18V/-5V...0V
- Soft body diode with low Vds overshoot and ringing
- Low Rds(on) at high operating temperatures
- Improved device capacitances ratio (Ciss/Crss)
- High transient voltage robustness with improved lifetime
- Halogen free, RoHS compliant
- Automotive Qualified (AEC-Q101) and PPAP Capable

Benefits

- Higher efficiency with lower switching losses and EMI
- Faster switching operation enabling high power density
- Enables system level price performance optimization
- Reduction in system level cooling requirements

Typical Applications

- Motor Control
- EV On Board Battery Chargers (OBC)
- Automotive DC/DC Converters for EV/HEV

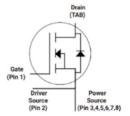


Package









Orderable Part number	Package type	Marking
E4MS065120J2-TR	TO-263-7XL	E4MS065120J2

Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note
Drain - Source Voltage	V _{DS}			1200	.,		
Maximum Gate - Source Voltage	V _{GS(max)}	-10		+23	V		
				36		$V_{GS} = 18 \text{ V}, T_{C} = 25 \text{ °C}, T_{J}$ $\leq 175 \text{ °C}$	
DC Continuous Drain Current	l _D			26	A	$V_{GS} = 18 \text{ V}, T_{C} = 100 \text{ °C}, T_{J}$ $\leq 175 \text{ °C}$	Note 1
Pulsed Drain Current	I _{DM}			105		t_{pmax} limited by T_{jmax} $V_{GS} = 18V, T_{C} = 25 °C$	
Power Dissipation	P _D			163	W	$T_{c} = 25^{\circ}C, T_{J} = 175^{\circ}C$	Note 2
Operating Junction and Storage Temperature	T _J , T _{stg}	-55		+175	0.5		
Solder Temperature	T _L			260	°C		

Note (1): Current limit calculated by $I_{D(max)} = \sqrt{(P_D/R_{DS(typ)}(T_{J(max)},I_{D(max)}))}$ Note (2): $P_D = (T_J - T_C)/R_{th(JC,max)}$

Electrical Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Min.	Тур.	Max.	Unit	Test Conditions	Note
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	1200			V	$V_{GS} = 0 \text{ V, } I_D = 100 \mu\text{A}$	İ
V	Cata Thuash ald Valta us	2	2.6	3.9	V	$V_{DS} = V_{GS}$, $I_D = 4.16 \text{ mA}$	Fig. 11
$V_{GS(th)}$	Gate Threshold Voltage		2.0		V	$V_{DS} = V_{GS}$, $I_D = 4.16$ mA, $T_J = 175$ °C	Fig. 11
I _{DSS}	Zero Gate Voltage Drain Current		1	50	μΑ	$V_{DS} = 1200 \text{ V}, V_{GS} = 0 \text{ V}$	
l _{GSS}	Gate-Source Leakage Current		10	250	nA	$V_{GS} = 18 \text{ V}, V_{DS} = 0 \text{ V}$	
$V_{GS(op)}$	Recommended Turn on Gate-Source Voltage		+15+18		V		Refer to PRD-
GS(op)	Recommended Turn off Gate-Source Voltage	ļ	-50				09634
			65	85		$V_{GS} = 18 \text{ V}, I_D = 15.1 \text{ A}$	
$R_{DS(on)}$	Drain-Source On-State Resistance		116		mΩ	V _{GS} = 18 V, I _D = 15.1 A, T _J = 175°C	Fig. 4, 5, 6
		-	71			V _{GS} = 15 V, I _D = 15.1 A	
g_{fs}	Transconductance		11		S	$V_{DS} = 20 \text{ V}, I_D = 15.1 \text{ A}, T_J = 25^{\circ}\text{C}$	Fig. 7
	1	+	10			V _{DS} = 20 V, I _D = 15.1 A, T _J = 175°C	
$R_{DS(on)Tempco}$	On resistance temperature coefficient		1.88			$V_{GS} = 18 \text{ V}, I_D = 15.1 \text{ A}$	Note 3
C _{iss}	Input Capacitance	ļ	1225		_		
C_{oss}	Output Capacitance		47		pF	$V_{GS} = 0 \text{ V}, V_{DS} = 1000 \text{ V}$ f = 100 kHz $V_{AC} = 25 \text{ mV}$	Fig. 17, 18
C_{rss}	Reverse Transfer Capacitance		2.4				
C_{iss}/C_{rss}	Capacitance Ratio		630				Note 4
E _{oss}	Coss Stored Energy		30		μЈ		Fig. 16
$C_{o(er)}$	Effective Output Capacitance (Energy Related)		68		_	V _{GS} = 0V, V _{DS} = 0800V	
C _{o(tr)}	Effective Output Capacitance (Time Related)		108		pF		
	Turn-On Switching Energy (Body Diode FWD)						
E _{on}	Tj=25C		164				Fig. 26, 29, 31
	Tj=175C		193			$V_{DS} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}, I_{D} = 15.1 \text{ A},$	
	Turn-Off Switching Energy (Body Diode FWD)	İ			· μJ	$R_{G(ext)} = 2\Omega, L\sigma = 25nH$	
E_{off}	Tj=25C		19				Fig. 26, 29, 32
	Tj=175C		20				32
t _{d(on)}	Turn-On Delay Time		9			$V_{DD} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}$	
t _r	Rise Time		2		[$V_{DD} = 800 \text{ V}, V_{GS} = -4 \text{ V/18 V}$ $I_D = 15.1 \text{ A}, R_{G(ext)} = 2\Omega,$ Timing relative to V_{DS} Inductive load	
$t_{d(off)}$	Turn-Off Delay Time		21		ns		Fig. 27, 28
t _f	Fall Time		10				
$R_{G(int)}$	Internal Gate Resistance		3.1		Ω	f = 1 MHz	
Q_{gs}	Gate to Source Charge		14			$V_{DS} = 800 \text{ V}, V_{GS} = -4 \text{ V}/18 \text{ V}$	
Q_{gd}	Gate to Drain Charge		12		nC	$I_D = 15.1 \text{ A}, T_J = 25^{\circ}\text{C}$	Fig. 12
Qg	Total Gate Charge		51		1	Per IEC60747-8-4 pg 21	

Note (3): $R_{DS(on)Tempco}$ refers to $R_{DS(on)}$ at 175 C/ $R_{DS(on)}$ at 25C, E4MS 1200V product family value

Note (4): Capacitance ratio is a FOM for Partial turn-on immunity PRD-06933, E4MS 1200V product family value

Co(er), a lumped capacitance that gives the same stored energy as Coss while Vds is rising from 0 to 800V Co(tr), a lumped capacitance that gives the same charging time as Coss while Vds is rising from 0 to 800V

Reverse Diode Characteristics (T_c = 25°C unless otherwise specified)

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
V	Diada Fawyard Valtaga	5.1		V	$V_{GS} = -4 \text{ V}, I_{SD} = 7.6 \text{ A}, T_{J} = 25 \text{ °C}$	Fig. 8, 9,
V _{SD}	Diode Forward Voltage	4.5		V	$V_{GS} = -4 \text{ V, } I_{SD} = 7.6 \text{ A, } T_{J} = 175 \text{ °C}$	10
Is	Continuous Diode Forward Current		25	А	$V_{GS} = -4 \text{ V, } T_C = 25^{\circ}\text{C}$	
I _{SM}	Diode Pulse Current		105	А	$V_{GS} = -4 \text{ V}$, pulse width t_p limited by T_{jmax} max	
t _{rr}	Reverse Recovery Time	11		ns		
Q _{rr}	Reverse Recovery Charge	325		nC	V _{GS} =-4 V, I _s =15.1 A, V _{SD} =800V - T,=175°C, diF/dt= 12.1 A/ns	
I _{RRM}	Peak Reverse Recovery current	57		А	1 ₁ =173°C, dir/dt=12.1 A/IIS	
	Reverse recovery Energy				V _{cc} =800 V, I _s =15.1 A,	
E _{RR}	Tj=25C	45		μЈ	V _{DS} =800 V, I _D =15.1 A,	
	Tj= 175C	87			V_{GS} =-4V/18V, $R_{G(on)}$ =2 Ω , $L\sigma$ =25nH	

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.71	0.92	°C/W		

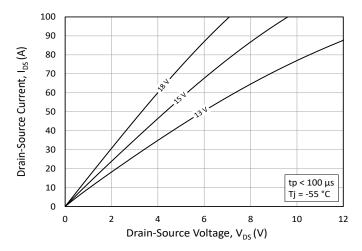


Figure 1. Output Characteristics T_J = -55°C

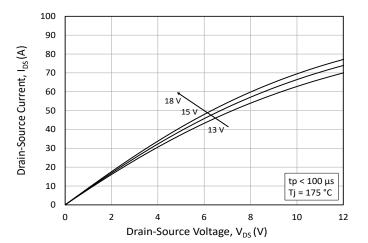


Figure 3. Output Characteristics T_J = 175°C

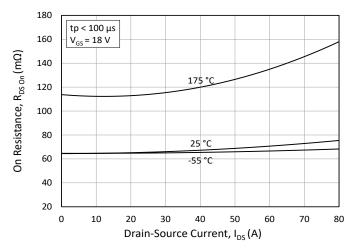


Figure 5. On-Resistance vs. Drain Current For Various Temperatures

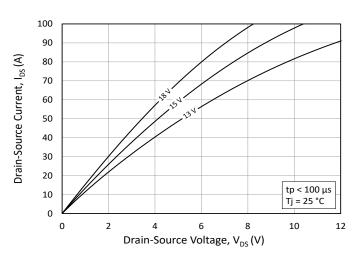


Figure 2. Output Characteristics $T_1 = 25$ °C

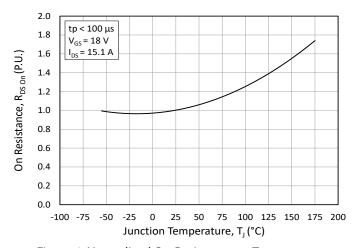


Figure 4. Normalized On-Resistance vs. Temperature

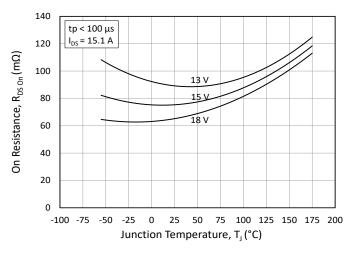


Figure 6. On-Resistance vs. Temperature For Various Gate Voltage

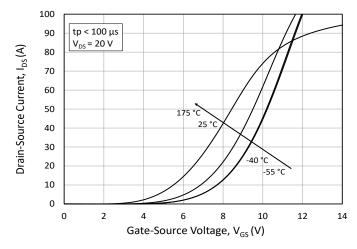


Figure 7. Transfer Characteristic for Various Junction Temperatures

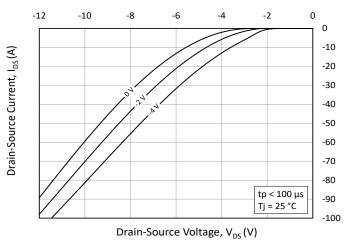


Figure 9. Body Diode Characteristic at 25°C

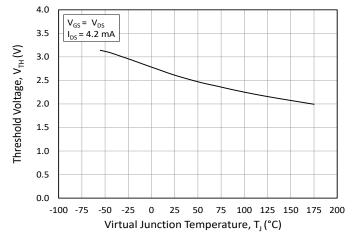


Figure 11. Threshold Voltage vs. Temperature

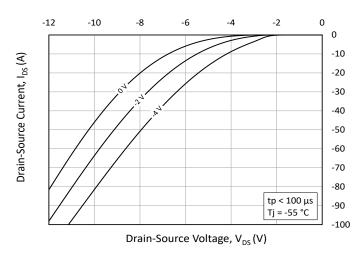


Figure 8. Body Diode Characteristic at -55°C

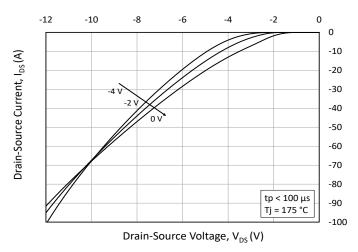


Figure 10. Body Diode Characteristic at 175°C

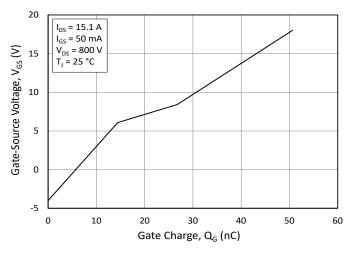


Figure 12. Gate Charge Characteristics

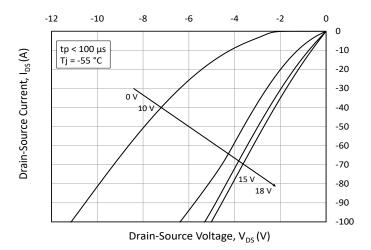


Figure 13. 3rd Quadrant Characteristic at -55°C

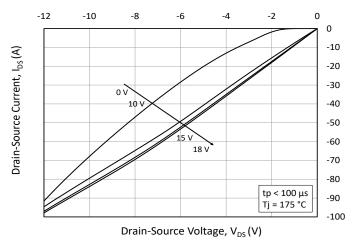


Figure 15. 3rd Quadrant Characteristic at 175°C

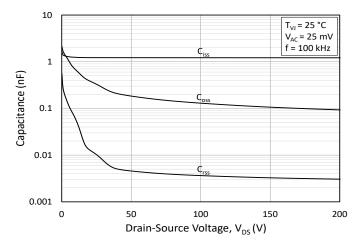


Figure 17. Capacitances vs. Drain-Source Voltage (0 - 200 V)

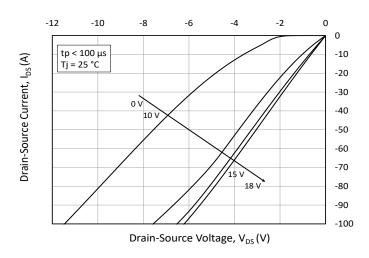


Figure 14. 3rd Quadrant Characteristic at 25°C

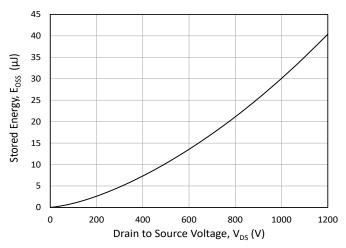


Figure 16. Output Capacitor Stored Energy

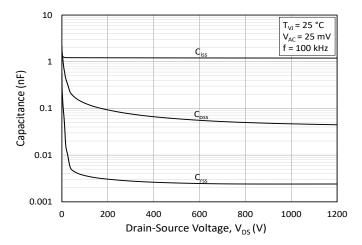


Figure 18. Capacitances vs. Drain-Source Voltage (0 - 1200 V)

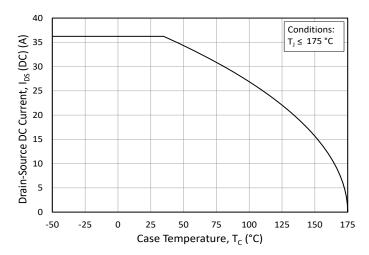


Figure 19. Continuous Drain Current Derating vs.

Case Temperature

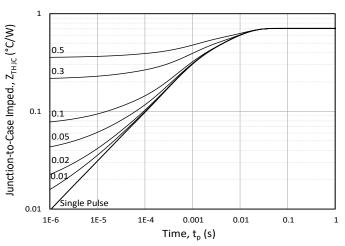


Figure 21. Transient Thermal Impedance (Junction - Case)

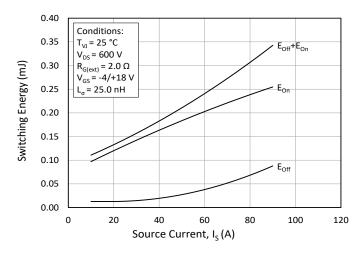


Figure 23. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 600 \text{ V}$)

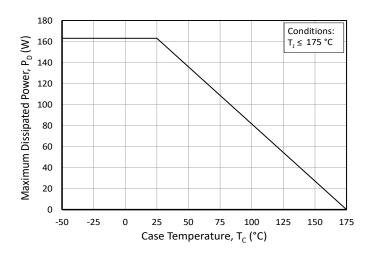


Figure 20. Maximum Power Dissipation Derating vs.

Case Temperature

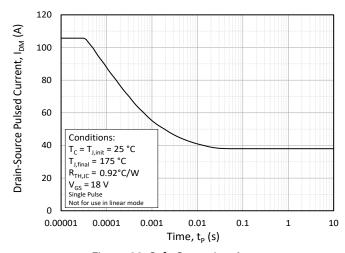


Figure 22. Safe Operating Area

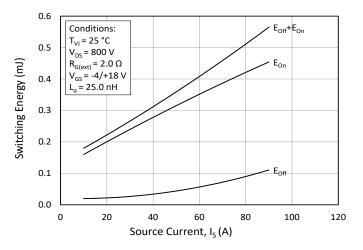


Figure 24. Clamped Inductive Switching Energy vs. Drain Current ($V_{DD} = 800 \text{ V}$)

Typical Performance

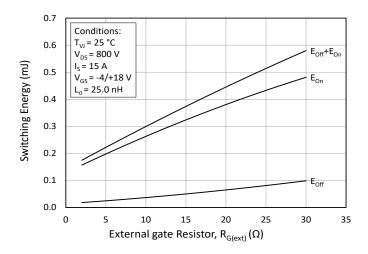


Figure 25. Clamped Inductive Switching Energy vs. $R_{G(ext)}$

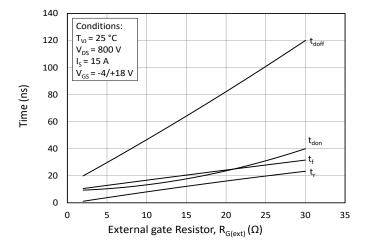


Figure 27. Switching Times vs. $R_{G(ext)}$

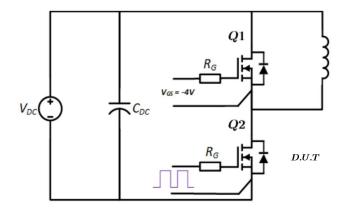
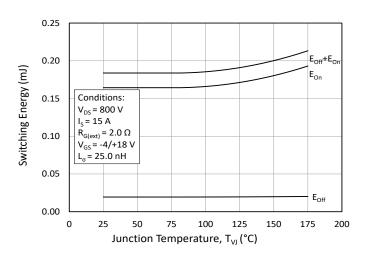


Figure 29. Clamped Inductive MOSFET Switching Waveform Test Circuit



8

Figure 26. Clamped Inductive Switching Energy vs.
Temperature

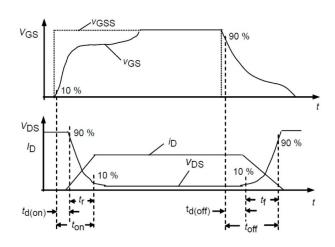


Figure 28. Switching Times Definition

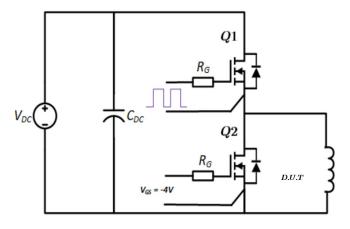
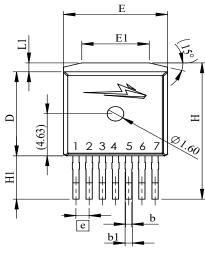
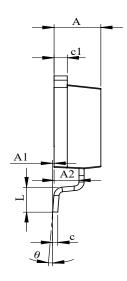
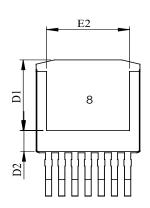


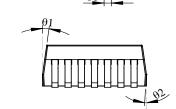
Figure 30. Clamped Inductive Body diode Switching Waveform Test Circuit

Package Dimensions









SYMBOL	MIN (mm)	MAX (mm)
A	4.30	4.70
A1	0.00	0.25
A2	2.20	2.60
b	0.52	0.72
b1	0.60	0.80
c	0.42	0.62
c1	1.07	1.47
D	9.05	9.45
D1	7.58	7.98
D2	2.05	2.45
Е	9.80	10.20
E1	6.30	6.97
E2	7.80	8.20
e	1.27	BSC
Н	14.87	15.27
H1	4.55	4.95
L	2.48	2.88
L1	0.87	1.27
θ	0°	8°
θ1	4°	10°
θ2	0°	6°

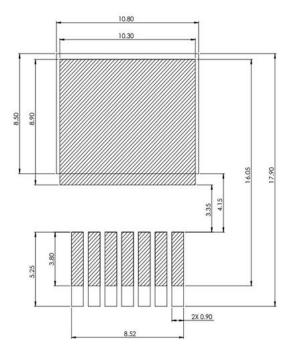
GATE						
KELVIN						
SOURCE						
DRAIN						

NOTE

- 1. ALL METAL SURFACES ARE TIN PLATED (MATTE), EXCEPT AREA OF CUT.
- 2. DIMENSIONING & TOLERANCING CONFORM TO ASME Y14.5M-1994.
- 3. ALL DIMENSIONS ARE LISTED IN MILLIMETERS. ANGLES ARE IN DEGREES.
- 4. PACKAGE BURR FLASH SIZE (0.5 mm) IS NOT INCLUDED IN THE DIMENSIONS

Recommended Solder Pad Lavout

All dimensions in mm



Revision history

Document Version	Date of release	Description of changes
1	November 2025	Initial release

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REACh Compliance

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